Special Issue

Advances in Electronics Packaging Materials and Technology

Message from the Guest Editor

Packaging materials and technologies used in electronic products have continued to evolve with the advancement of science and technology. Electronic packaging includes various insulators, conductors, and polymer technologies to protect electronic products. With the recent emergence of mobile devices such as smartphones, packaging technology has been continuously developed to improve the reliability of manufacturing high-performance electronic products in a limited space. In the future, new technologies such as artificial intelligence, the Internet of Things, and robotics will help in developing ever more complex electronic products. Along with developing these products, electronic packaging technology is expected to develop further. Semiconductors show pattern accuracy at the 3nm level. Since high-performance semiconductor chips must be integrated into the limited space of a smartphone, related packaging technology has had to develop dramatically. In addition, in the case of secondary batteries, their use is expanding due to the rapid increase in electric vehicles.

Guest Editor

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Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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